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2823



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PTO/SB/21 (08-00)

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TRANSMITTAL FORM

(To be used for all correspondence after initial filing)

Application Number	09/632,388
Filing Date	August 3, 2000
First Named Inventor	Shin Hwa Li
Group Art Unit	2823
Examiner Name	Julio J. Maldonado
Attorney Docket No.	98-P-009C2 (850063.529C1)

ENCLOSURES (check all that apply)

<input type="checkbox"/> Fee Transmittal Form <input type="checkbox"/> Fee Attached <input checked="" type="checkbox"/> Amendment/Response <input type="checkbox"/> After Final <input type="checkbox"/> Affidavits/declaration(s) <input type="checkbox"/> Extension of Time Request <input type="checkbox"/> Express Abandonment Request <input type="checkbox"/> Information Disclosure Statement; Form PTO-1449 <input type="checkbox"/> Cited References <input type="checkbox"/> Certified Copy of Priority Document(s) <input type="checkbox"/> Response to Missing Parts under 37 C.F.R. 1.52 or 1.53 <input type="checkbox"/> Response to Missing Parts/Incomplete Application	<input type="checkbox"/> Assignment Papers (for an Application) <input type="checkbox"/> Drawing(s) <input type="checkbox"/> Request for Corrected Filing Receipt <input type="checkbox"/> Licensing-related Papers <input type="checkbox"/> Petition <input type="checkbox"/> Petition to Convert to a Provisional Application <input type="checkbox"/> Power of Attorney, Revocation, Change of Correspondence Address <input type="checkbox"/> Declaration <input type="checkbox"/> Statement under 37 CFR 3.73(b) <input type="checkbox"/> Terminal Disclaimer <input type="checkbox"/> Small Entity Statement <input type="checkbox"/> Request for Refund	<input type="checkbox"/> CD(s), Number of CD(s) _____ <input type="checkbox"/> After Allowance Communication to Group <input type="checkbox"/> Appeal Communication to Board of Appeals and Interferences <input type="checkbox"/> Appeal Communication to Group (Appeal Notice, Brief, Reply Brief) <input type="checkbox"/> Proprietary Information <input type="checkbox"/> Status Letter <input checked="" type="checkbox"/> Return Receipt Postcard <input type="checkbox"/> Additional Enclosure(s) (please identify below): _____ _____ _____ _____
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Remarks

SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT

Individual Name	Brian L. Johnson	 30423 PATENT TRADEMARK OFFICE
Signature		
Date	August 6, 2002	

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EXPRESS MAIL NO. EV064841480US

Hawkins
PATENT 8/13/02

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Shin Hwa Li et al.
Application No. : 09/632,388
Filed : August 3, 2000
For : SEMICONDUCTOR STRUCTURE HAVING AN IMPROVED
PRE-METAL DIELECTRIC STACK AND METHOD FOR
FORMING THE SAME

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Examiner : Julio J. Maldonado
Art Unit : 2823
Docket No. : 98-P-009C2 (850063.529C1)
Date : August 6, 2002

Box Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

AMENDMENT

Commissioner for Patents:

In response to the office action dated May 6, 2002 (the "Office Action"), please amend the application as follows:

In the Specification:

Please replace the paragraph beginning at page 4, line 10, with the following rewritten paragraph:

F1
Referring to Figure 4, a layer 38 is formed over the BPSG layer 6 before CMP. In one embodiment, the layer 38 is conventionally formed from plasma-enhanced tetraethyl orthosilicate (PE-TEOS). The layer 38 acts as a sacrificial layer for the CMP process. In one embodiment, the thickness of the layer 38 is between approximately 8,000 – 20,000 angstrom, for example about 12,000 angstroms. The thickness of the BPSG layer 6 is between approximately 1,500 – 8,000 angstroms, for example 6,000 angstroms. The thickness of the